

# 40V +175°C N-CHANNEL ENHANCEMENT MODE MOSFET PowerDI5060-8

### **Product Summary**

		ID	
BV <sub>DSS</sub>	R <sub>DS(ON)</sub> Max	T <sub>C</sub> = +25°C (Note 9)	
		(11010-0)	
40V	$1.0 m\Omega$ @ V <sub>GS</sub> = 10V	100A	

#### **Features**

- Rated to +175°C Ideal for High Ambient Temperature Environments
- 100% Unclamped Inductive Switching (UIS) Test in Production Ensures More Reliable and Robust End Application
- Thermally Efficient Package-Cooler Running Applications
- High Conversion Efficiency
- Low R<sub>DS(ON)</sub> Minimizes On State Losses
- <1.1mm Package Profile Ideal for Thin Applications
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- The DMTH4001SPSQ is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.

https://www.diodes.com/quality/product-definitions/

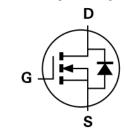
## **Description and Applications**

This MOSFET is designed to meet the stringent requirements of Automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

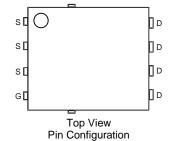
- Engine Management Systems
- Body Control Electronics
- DC-DC Converters

#### **Mechanical Data**

- Case: PowerDI<sup>®</sup>5060-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Finish Matte Tin Annealed over Copper Leadframe.
   Solderable per MIL-STD-202, Method 208 (§3)
- Weight: 0.097 grams (Approximate)



Internal Schematic



PowerDI5060-8 (Type K)





Top View

**Bottom View** 

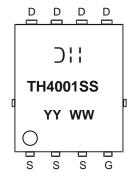
#### **Ordering Information** (Note 4)

Part Number	Case	Packaging
DMTH4001SPSQ-13	PowerDI5060-8 (Type K)	2,500 / Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

## **Marking Information**



☐ ☐ Manufacturer's Marking
TH4001SS = Product Type Marking Code
YYWW = Date Code Marking
YY = Last Two Digits of Year (ex: 20 = 2020)
WW = Week Code (01 to 53)

PowerDI is a registered trademark of Diodes Incorporated.



## **Maximum Ratings** (@ $T_A = +25^{\circ}C$ , unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	VDSS	40	V	
Gate-Source Voltage	Vgss	±20	V	
Continuous Drain Current, V <sub>GS</sub> = 10V (Notes 6 & 9)	$T_C = +25$ °C $T_C = +100$ °C	lD	100 100	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	I <sub>DM</sub>	400	Α	
Continuous Body Diode Forward Current (Notes 6 & 9)	ls	100	Α	
Pulsed Body Diode Forward Current (10µs Pulse, Duty Cycle = 1%)	Ism	400	Α	
Avalanche Current, L = 0.1mH	las	93.8	Α	
Avalanche Energy, L = 0.1mH	E <sub>AS</sub>	440	mJ	

### **Thermal Characteristics**

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	$T_A = +25^{\circ}C$	PD	3.09	W
Thermal Resistance, Junction to Ambient (Note 5)	RθJA	48	°C/W	
Total Power Dissipation (Note 6)	$T_C = +25^{\circ}C$	P <sub>D</sub>	187.5	W
Thermal Resistance, Junction to Case (Note 6)		R <sub>θ</sub> JC	0.8	°C/W
Operating and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to +175	°C

## Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	40	_	_	V	$V_{GS} = 0V$ , $I_D = 1mA$	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_	_	1	μΑ	$V_{DS} = 32V, V_{GS} = 0V$	
Gate-Source Leakage	Igss	_	_	±100	nA	$V_{GS} = \pm 20V$ , $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	2	2.61	4	V	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$	
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	_	0.73	1.0	mΩ	$V_{GS} = 10V, I_D = 30A$	
Diode Forward Voltage	$V_{SD}$	_	0.7	1.3	V	$V_{GS} = 0V, I_{S} = 20A$	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	Ciss		10787	_		V <sub>DS</sub> = 20V, V <sub>GS</sub> = 0V, f = 1MHz	
Output Capacitance	Coss	_	3929	_	pF		
Reverse Transfer Capacitance	Crss	_	156	_			
Gate Resistance	$R_g$	_	3.71	_	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$	
Total Gate Charge	Qg	_	144	_		V <sub>DD</sub> = 20V, I <sub>D</sub> = 50A, V <sub>GS</sub> = 10V	
Gate-Source Charge	Qgs	_	40	_	nC		
Gate-Drain Charge	$Q_{gd}$	_	24	_			
Turn-On Delay Time	td(ON)	_	11	_		$V_{DD} = 20V$ , $V_{GS} = 10V$ , $I_{D} = 50A$ , $R_{g} = 2.5\Omega$	
Turn-On Rise Time	t <sub>R</sub>	_	44	_			
Turn-Off Delay Time	tD(OFF)	_	85	_	ns		
Turn-Off Fall Time	t <sub>F</sub>		38	_			
Reverse Recovery Time	trr	_	68	_	ns	I <sub>F</sub> = 15A, di/dt = 100A/µs	
Reverse Recovery Charge	Q <sub>RR</sub>	_	110	_	nC	-1F = 13A, α/αι = 100A/μS	

Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate. 6. Thermal resistance from junction to soldering point (on the exposed drain pad).

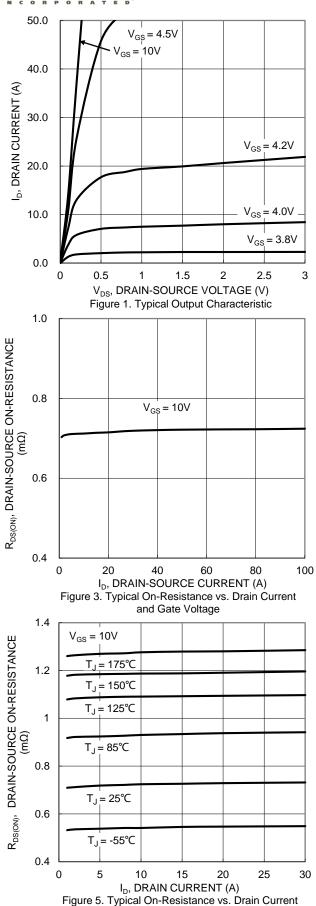
9. Limited by package..

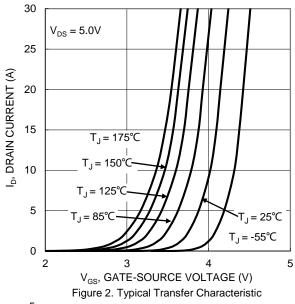
<sup>7.</sup> Short duration pulse test used to minimize self-heating effect.

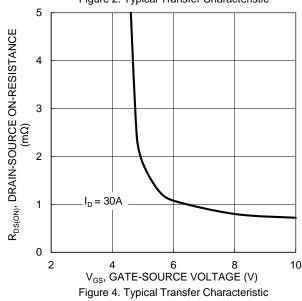
Short duration pulse test used to minimize sen-neating.
 Guaranteed by design. Not subject to product testing.











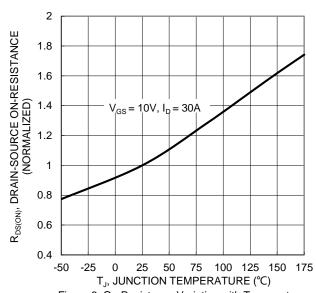


Figure 6. On-Resistance Variation with Temperature

and Temperature





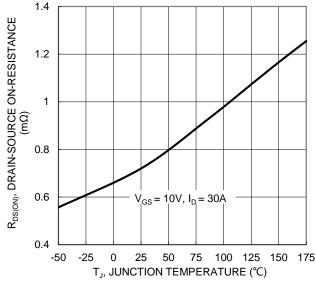


Figure 7. On-Resistance Variation with Temperature

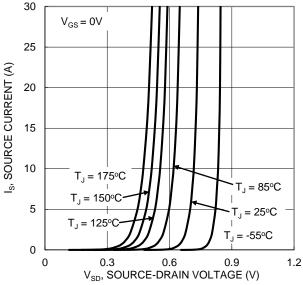
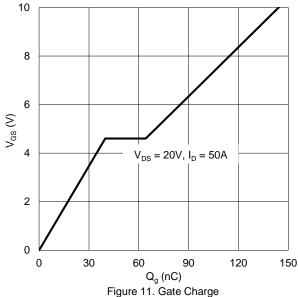
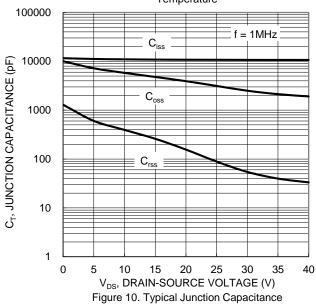


Figure 9. Diode Forward Voltage vs. Current



4 V<sub>GS(TH)</sub>, GATE THRESHOLD VOLTAGE (V) 3.5 3  $I_D = 1mA$ 2.5 2  $I_{D} = 250 \mu A$ 1.5 1 0.5 0 50 75 100 125 150 175 -50 -25 0 25 T<sub>J</sub>, JUNCTION TEMPERATURE (°C)

Figure 8. Gate Threshold Variation vs. Junction Temperature



1000 Limited 100 ID, DRAIN CURRENT (A) DC P<sub>W</sub> = 100ms  $P_W = 10 ms$ 10  $T_{J(Max)} = 175$ °C  $P_W = 100 \mu s$  $T_C = 25^{\circ}C$ Single Pulse DUT on Infinite Heatsink  $V_{GS} = 10V$ 0.1 0.1 100  ${
m V_{DS}}, {
m DRAIN}\mbox{-SOURCE VOLTAGE}$  (V) Figure 12. SOA, Safe Operation Area



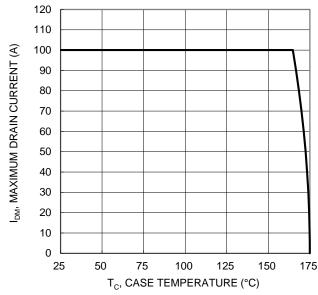


Figure 13. Pulse Current Derating

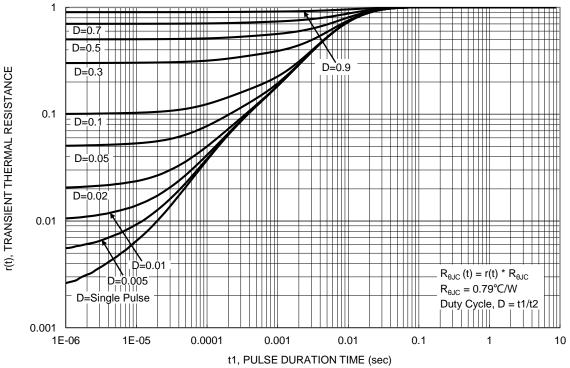


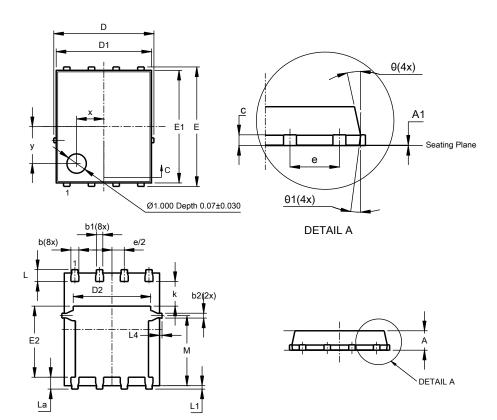
Figure 14. Transient Thermal Resistance



## **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### PowerDI5060-8 (Type K)

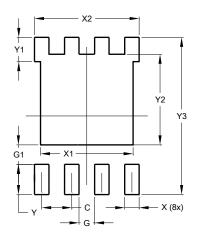


PowerDI5060-8 (Type K)				
Dim	Min	Max	Тур	
Α	0.90	1.10	1.00	
A1	0	0.05	0.02	
b	0.33	0.51	0.41	
b1	0.300	0.366	0.333	
b2	0.20	0.35	0.25	
С	0.23	0.33	0.277	
D	5	.15 BS0		
D1	4.85	4.95	4.90	
D2	-	-	3.98	
Е		.15 BS0		
E1	5.75	5.85	5.80	
E2	3.56	3.725	3.66	
е	1	.27BSC		
k	-	-	1.27	
L	0.51	0.71	0.61	
La	0.51	0.675	0.61	
L1	0.05	0.20	0.175	
L4	-	-	0.125	
M	3.50	3.71	3.605	
Х	-	-	1.400	
у	-	-	1.900	
θ	10°	12°	11°	
θ1	6°	8°	7°	
All Dimensions in mm				

## **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### PowerDI5060-8 (Type K)



Dimensions	Value		
Difficusions	(in mm)		
С	1.270		
G	0.660		
G1	0.820		
Х	0.610		
X1	3.910		
X2	4.420		
Υ	1.270		
Y1	1.020		
Y2	3.810		
Y3	6.610		



#### **IMPORTANT NOTICE**

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes Incorporated.

#### **LIFE SUPPORT**

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

- A. Life support devices or systems are devices or systems which:
  - 1. are intended to implant into the body, or
  - 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
- B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2020, Diodes Incorporated

www.diodes.com